

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: Masaru SHIRAI et al.

Group Art Unit: 1725

Serial No.: 10/598,142

Examiner: D'ANIELLO, N.

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**For: HEATER, REFLOW APPARATUS, AND SOLDER BUMP FORMING METHOD  
AND APPARATUS****REQUEST FOR EXTENSION OF TIME**

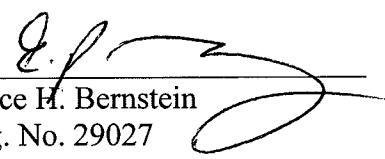
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Sir:

Please extend the time for response to the Official Action dated March 14, 2011 by one month from June 14, 2011 to July 14, 2011. The amount of \$130.00 is submitted concurrently herewith as payment for the fee.

The U.S. Patent and Trademark Office is hereby authorized to credit any overpayment or charge any additional fee to Deposit Account No.19-0089.

Respectfully submitted,  
Masaru SHIRAI et al.



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July 14, 2011  
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